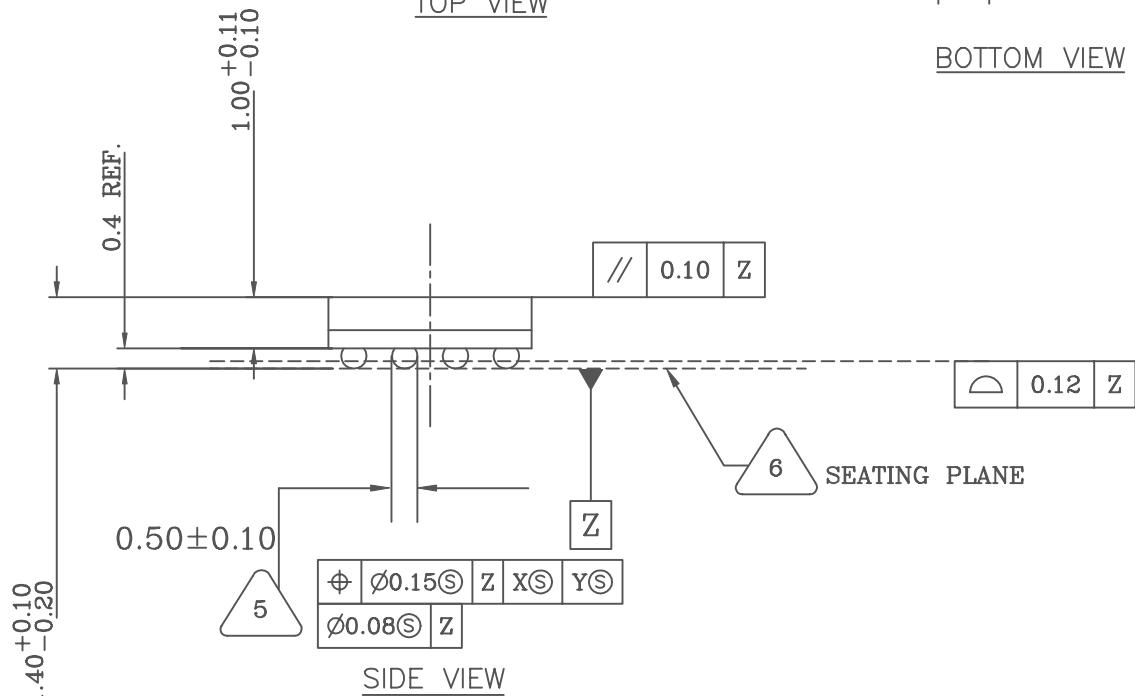
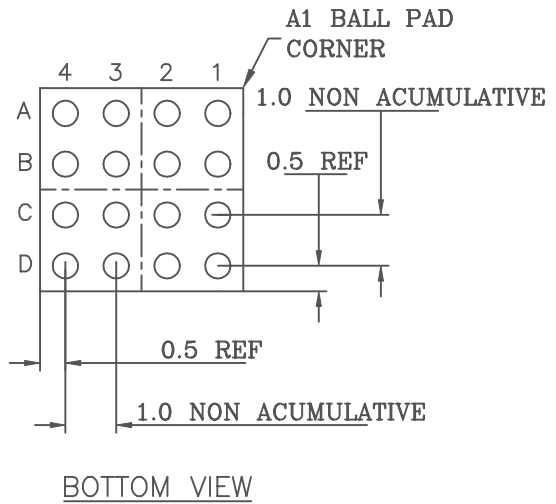
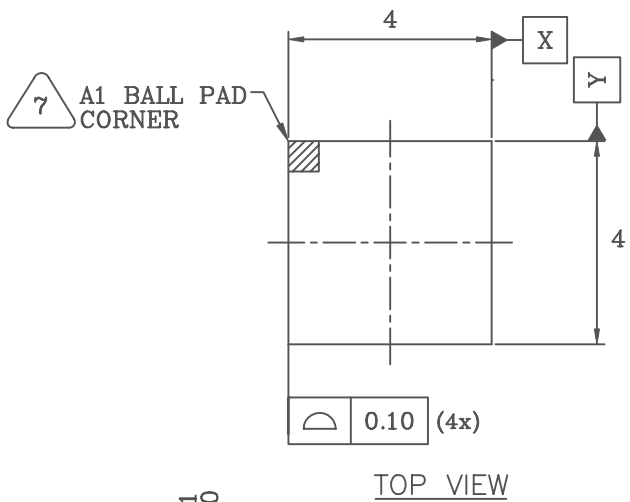


| REVISIONS | | | |
|-----------|----------------|-------|----------|
| LTR. | DESCRIPTION | DATE | APPROVED |
| A | NEW DRAWING | 3/00 | |
| B | PER ECN #38288 | 11/03 | |



NOTES:

- 7. A1 BALL PAD CORNER I.D. IS IDENTIFIED BY LASER MARKED DOT AT THE CORNER.
- 6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
- 4. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 3. SOLDER BALL POSITION DESIGNATION PER JESD 95-1, SPP-010.
- 2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- 1. ALL DIMENSIONS ARE IN MILLIMETERS

| | | | | | | | | | | | |
|----------------------|--|-------|--|------------|----------|---------------|------|--|--|--|--|
| SIGNATURE | | DATE | | | | | | | | | |
| DOC. CONTROL: | | | | | | | | TITLE | | | |
| ENGR. MGR: | | | | | | | | MARKETING OUTLINE - 16L CHIP SCALE BGA (4X4) 1.0MM PITCH, 1.40MM THICK, 2 LAYER | | | |
| MFG. ENGR: | | | | SIZE | FSCM NO. | PART NO. | REV. | | | | |
| CHECKED BY: TWM | | 11/03 | | A | | 56-G6005-001 | B | | | | |
| DRAWN BY: JFD | | 11/03 | | SCALE: N/A | | SHEET: 1 of 1 | | | | | |
| DO NOT SCALE DRAWING | | | | | | | | | | | |